Manufacturing Bulletin

Subject:  Removal of 2nd Level Interconnect Label
Date:    July 10, 2018

Integrated Device Technology, Inc. will remove 2nd Level Interconnect label on Reel, MBB, Shielding Bag & Pizza box for all the shipments in Reel, Tray & Tube form effective date 23 July, 2018. The purpose of this change is to standardize the labeling method used by all shipping locations and reduce the environmental waste due to excessive barcode label printing.

The minor changes as stated below:

1.) Remove 2nd Level Interconnect Label for orders with custom label.

   Note: Customer can request through IDT Sales if 2nd Level Interconnect label is needed in the shipment.

Kindly refer to the attachments for the 2nd Level Interconnect Label and the comparison before and after the change.

Please note that this change will not impact the custom barcode labels (barcode format per customer specification).

During the transition period, customer may receive shipments in previous and new labeling methods; however each shipment will contain either the new or old method and not mixed.

Yours sincerely,

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Attachment I

2nd Level Interconnect Label

2nd Level Interconnect

Pb-Free

1. Category = e3 Sn
2. Maximum safe temperature: 260 °C
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Attachment II

Label Comparison (Reel form)
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Attachment III

Label Comparison (Tray form)

Existing Label Pasting

New Label Pasting
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Attachment IV

Label Comparison (Tube form)

Existing Label Pasting

New Label Pasting